



## PATENT APPLICATION

Sheet 1 of 1

FORM PTO-1449

ATTY. DOCKET NO.

10031071-1

SERIAL NO.

10/769,250

LIST OF PATENTS AND PUBLICATIONS FOR  
APPLICANT'S INFORMATION DISCLOSURE  
STATEMENT

APPLICANT

Donald E. Schott, et al.

FILING DATE

1/30/04

GROUP

Unk 2800

(Use several sheets if necessary)

## REFERENCE DESIGNATION

## U.S. PATENT DOCUMENTS

EXAMINER INITIAL	*	DOCUMENT NUMBER	DATE	NAME
NH		6,108,212	8/22/00	Lach, et al.
NH		6,132,543	10/17/00	Mohri, et al.

## FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	NAME	TRANSLATION	
					YES	NO

## OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, etc.)

NH	X	Tongbi Jiang, et al., Composite Interposer For BGA Packages, US2003/0164556 A1 Published 9/4/2003.
NH	X	Binng Y. Lao, et al., Single And Multiple Layer Packaging Of High-Speed/High-Density ICS, US2003/0096447 A1 published 5/22/03.
NH	X	Chung Wen Ho, High Density Cavity-Up Wire Bond, US2001/0046725 A1 Published 11/29/01.

EXAMINER

DATE CONSIDERED

9-16-09

\* Copies of these references are not enclosed pursuant to 37 CFR 1.98(d). (See accompanying IDS)